

Features

- 20V/6.9A,
 $R_{DS(ON)} = 23m\Omega(Typ.)@V_{GS}=4.5V$
 $R_{DS(ON)} = 32m\Omega(Typ.)@V_{GS}=2.5V$
- Low $R_{DS(ON)}$
- Super High Dense Cell Design
- Reliable and Rugged

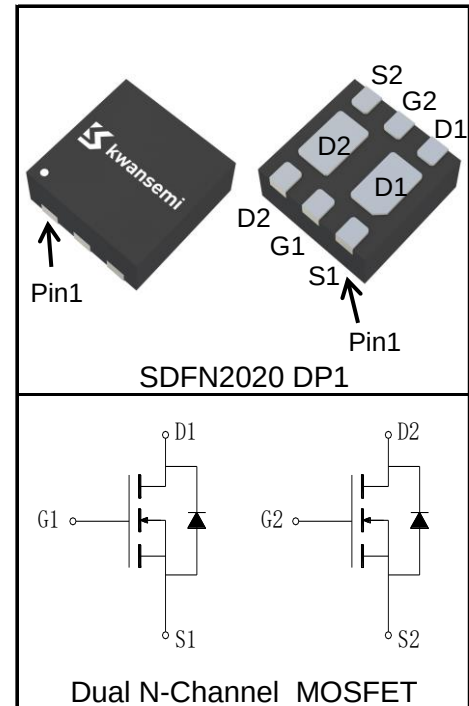
Applications

- Power Management
- Battery Protection



Halogen-Free

Pin Description



Absolute Maximum Ratings

Symbol	Parameter		Rating	Unit
Common Ratings (T _A =25°C Unless Otherwise Noted)				
V _{DSS}	Drain-Source Voltage		20	V
V _{GSS}	Gate-Source Voltage		±12	
T _J	Maximum Junction Temperature		150	°C
T _J ,T _{STG}	Operating and Storage Temperature Range		-55 to 150	°C
I _S	Diode Continuous Forward Current	T _A =25°C	2.3	A
Mounted on Large Heat Sink				
I _{DP} ^①	Pulse Drain Current	T _A =25°C	27	A
I _D ^②	Continuous Drain Current(V _{GS} =4.5V)	T _A =25°C	6.9	A
		T _A =70°C	5.5	
P _D	Maximum Power Dissipation	T _A =25°C	2	W
		T _A =70°C	1.25	
R _{θJC}	Thermal Resistance-Junction to Case		25	°C/W
R _{θJA} ^③	Thermal Resistance-Junction to Ambient		60	°C/W
Drain-Source Avalanche Ratings				
E _{AS} ^④	Avalanche Energy, Single Pulsed		20	mJ

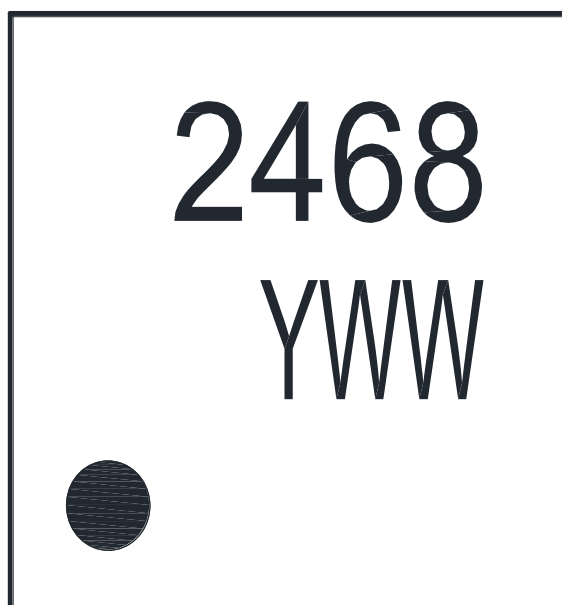
Electrical Characteristics ($T_A=25^{\circ}\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Condition	Rating			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	20			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V			1	μA
		T _J =125°C			30	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	0.5	0.7	1.1	V
I _{GSS}	Gate Leakage Current	V _{GS} =±12V, V _{DS} =0V			±100	nA
R _{DS(ON)} ⑤	Drain-Source On-state Resistance	V _{GS} =4.5V, I _{DS} =3A		23	28	mΩ
		V _{GS} =2.5V, I _{DS} =2A		32	42	mΩ
Diode Characteristics						
V _{SD} ⑤	Diode Forward Voltage	I _{SD} =3A, V _{GS} =0V		0.85	1.2	V
t _{rr}	Reverse Recovery Time	I _{SD} =3A, dI _{SD} /dt=100A/μs		21		ns
Q _{rr}	Reverse Recovery Charge			12		nC
Dynamic Characteristics ⑥						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz		2.5		Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =10V, Frequency=1.0MHz		415		pF
C _{oss}	Output Capacitance			70		
C _{rss}	Reverse Transfer Capacitance			60		
t _{d(ON)}	Turn-on Delay Time	V _{DD} =10V, I _{DS} =3A, V _{GEN} =4.5V, R _G =6Ω		11		ns
t _r	Turn-on Rise Time			15		
t _{d(OFF)}	Turn-off Delay Time			39		
t _f	Turn-off Fall Time			26		
Gate Charge Characteristics ⑥						
Q _g	Total Gate Charge	V _{DS} =10V, V _{GS} =4.5V, I _{DS} =3A		6		nC
Q _{gs}	Gate-Source Charge			0.8		
Q _{gd}	Gate-Drain Charge			1.9		

- Notes:
- ① Pulse width limited by safe operating area.
 - ② Calculated continuous current based on maximum allowable junction temperature.
 - ③ When mounted on 1 inch square copper board, $t \leq 10\text{sec}$. The value in any given application depends on the user's specific board design.
 - ④ Limited by T_{Jmax} , Starting $T_J = 25^{\circ}\text{C}$, $I_{ASmax} = 9A$, $L = 0.5\text{mH}$, $V_{DD} = 12V$, $R_G = 25\Omega$, $V_{GS} = 4.5V$. Part not recommended for use above this value.
 - ⑤ Pulse test; Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
 - ⑥ Guaranteed by design, not subject to production testing.

Ordering and Marking Information

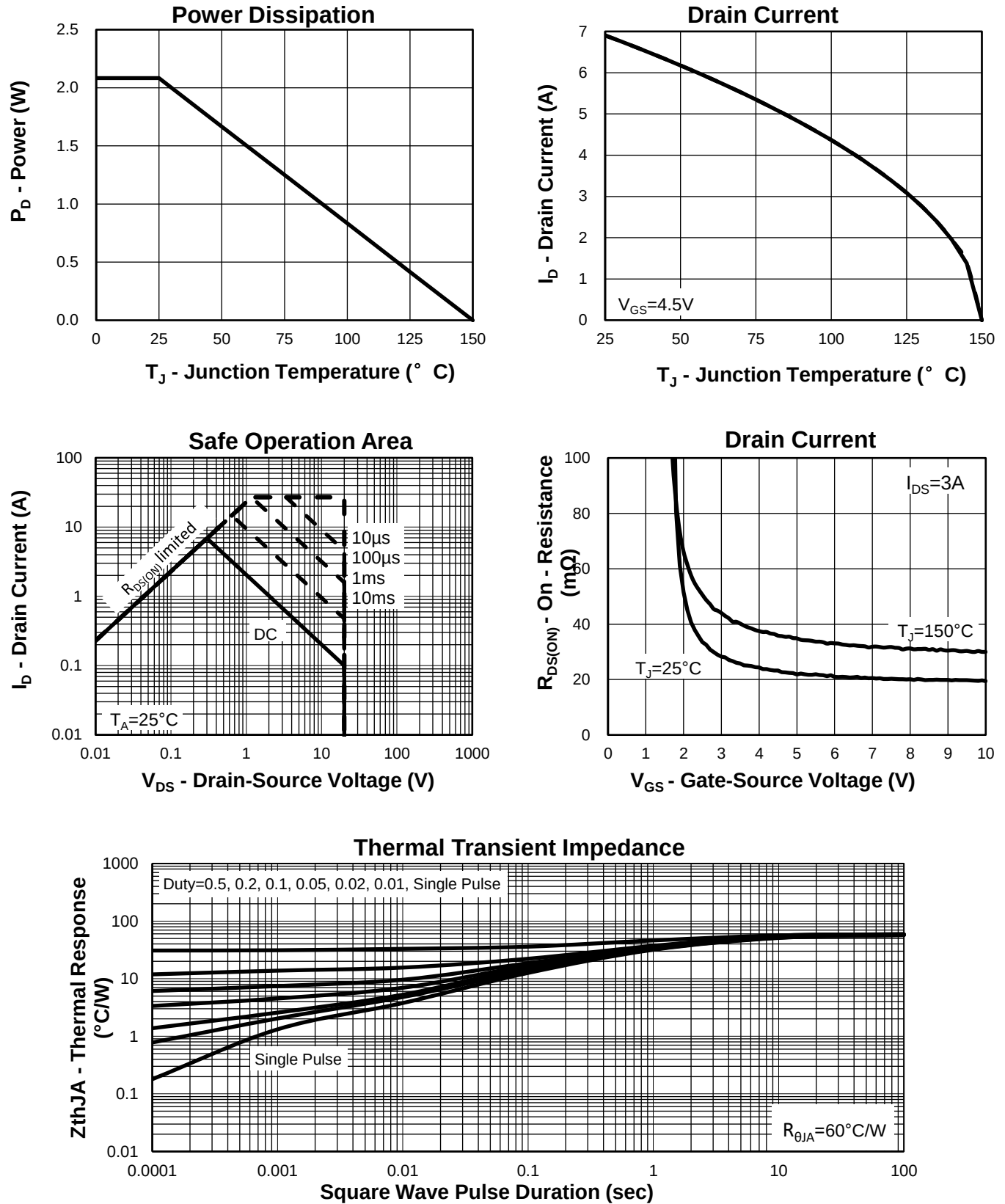
Device	Package	Packaging	Quantity	Reel Size	Tape width
KS2468UA2	SDFN2020 DP1	Tape&Reel	3000	7"	8mm



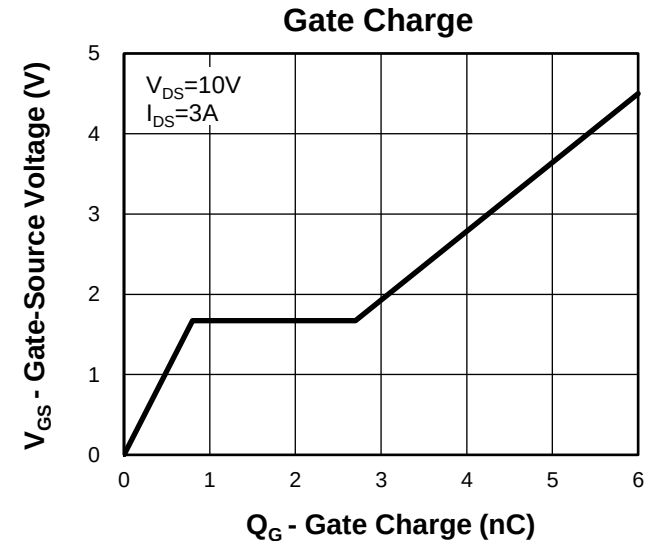
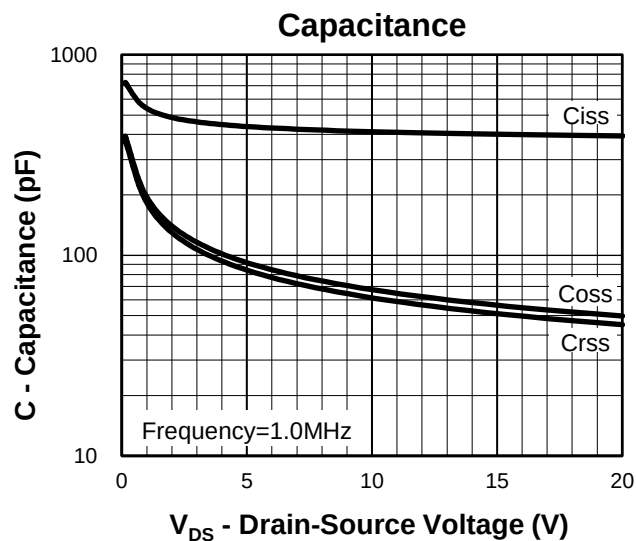
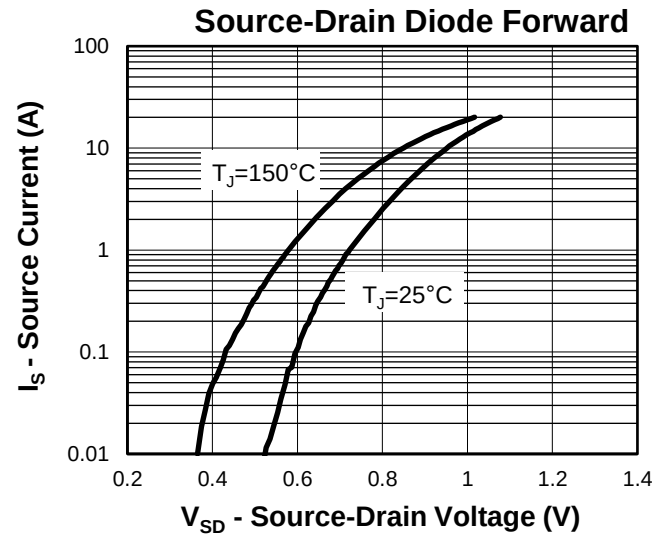
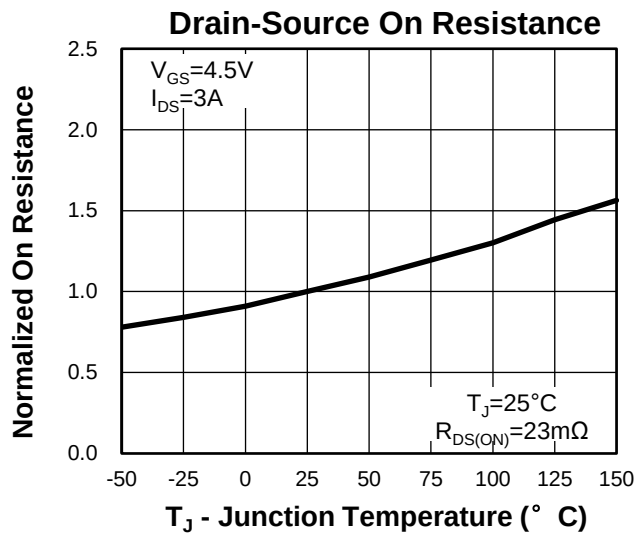
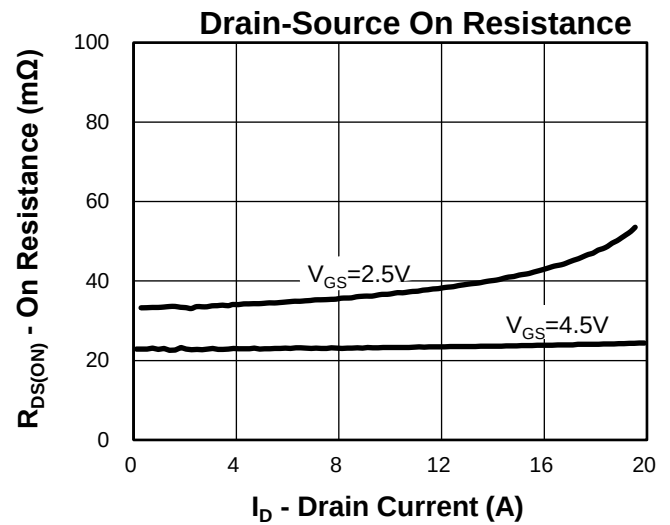
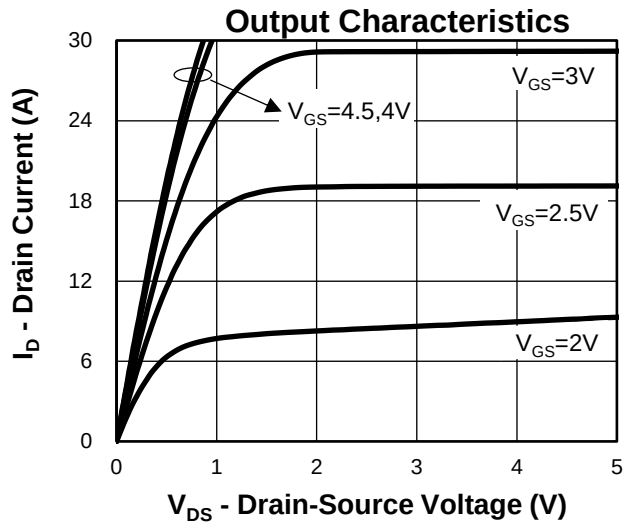
Y =Year,2017-A,2018-B,etc.

WW =Week.

Typical Characteristics

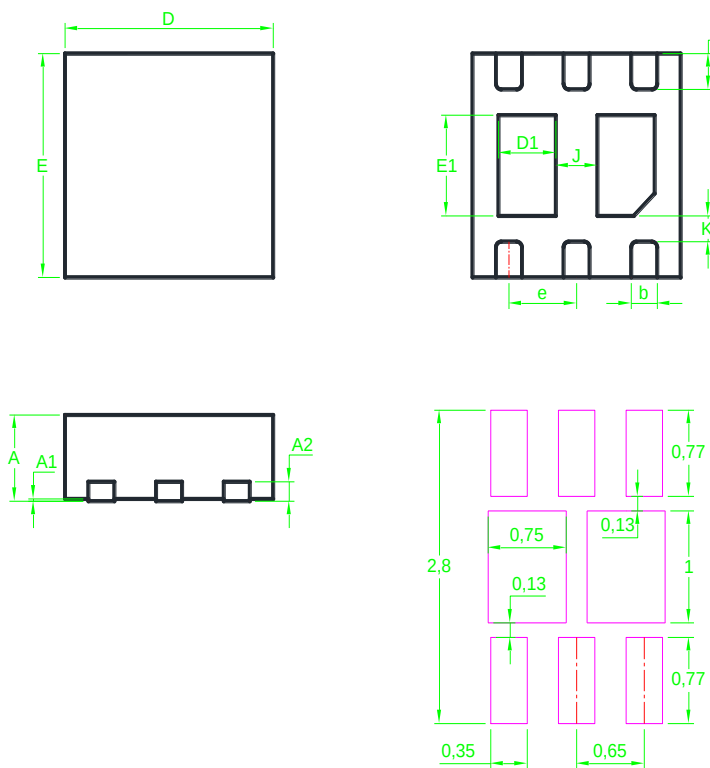


Typical Characteristics



Package Information

SDFN2020 DP1

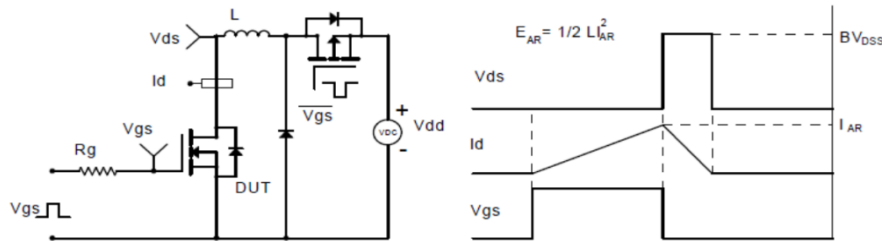


Land Pattern
(Only Reference)

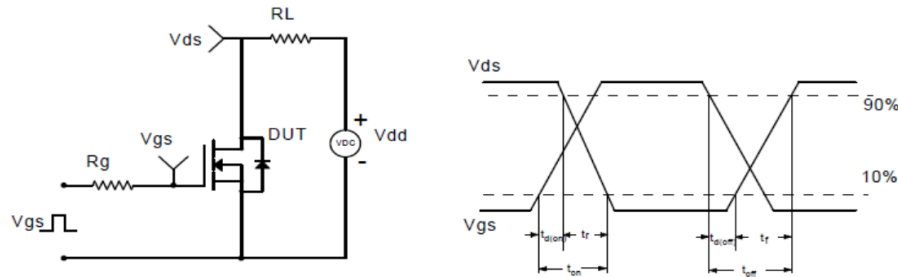
SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.75	0.80	0.028	0.030	0.031
A1	0.00	*	0.05	0.000	*	0.002
A2	0.203BSC			0.008BSC		
b	0.20	0.25	0.30	0.008	0.010	0.012
D	1.95	2.00	2.05	0.077	0.079	0.081
D1	0.50	0.55	0.60	0.020	0.022	0.024
e	0.65BSC			0.026BSC		
E	1.95	2.00	2.05	0.077	0.079	0.081
E1	0.85	0.90	0.95	0.050BSC		
L	0.27	0.32	0.37	0.011	0.013	0.015
J	0.40BSC			0.016BSC		
K	0.02	*	*	0.001	*	*

Note: Dimensions do not inclusive burrs and mold flash.

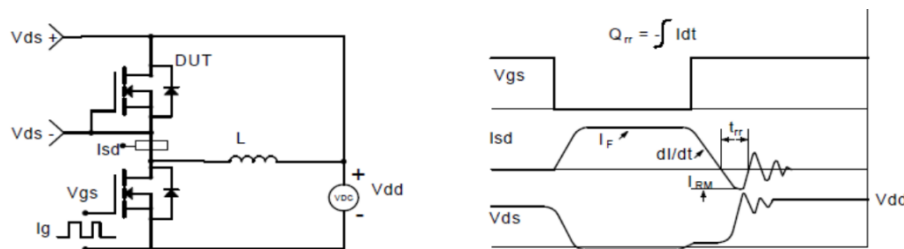
Avalanche Test Circuit and Waveforms



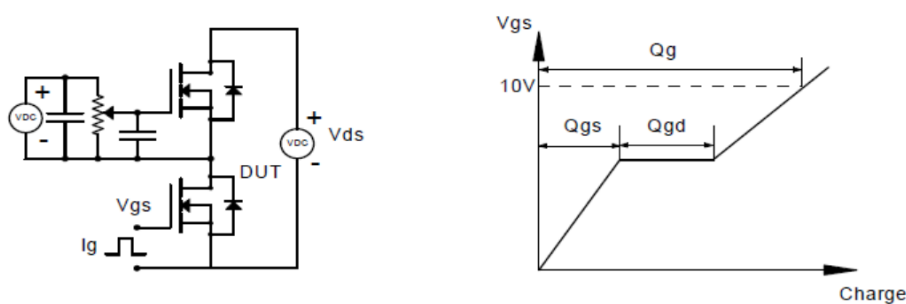
Switching Time Test Circuit and Waveforms



Diode Recovery Test Circuit and Waveforms



Gate Charge Test Circuit and Waveform



Customer Service

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